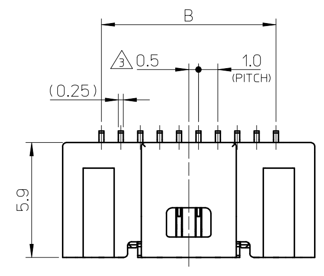
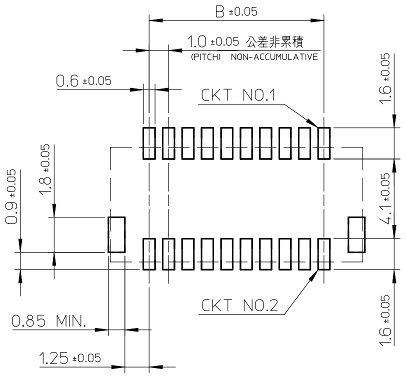
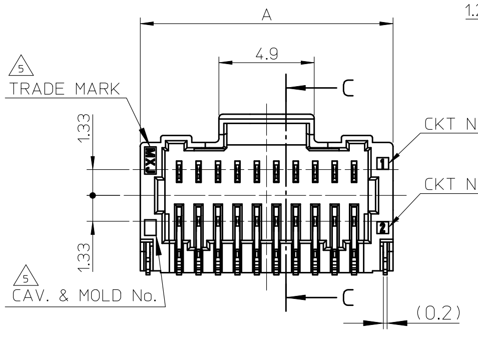
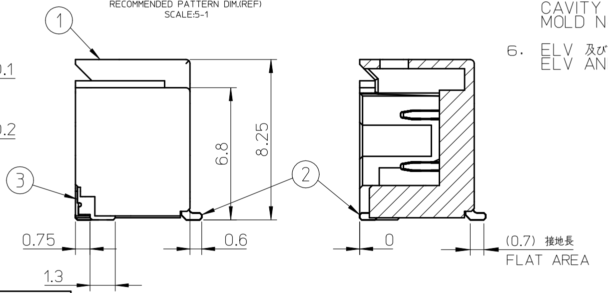




参考パターンレイアウト
RECOMMENDED PATTERN DIM.(REF)
SCALE:5-1





SECTION C-C

NOTES

1. 嵌合相手：501189-****
MATE WITH：501189-****

2. ソルダーピン及びネールの平坦度は0.1MAX.
SOLDER PIN AND NAIL COPLANRITY TO BE 0.1MAX.

△3 極数／2＝偶数極の場合に適用
APPLY FOR (CIRCUIT/2=EVEN

4. 製品番号
MATERIAL No.

501571 - **07 , 501571 - **5*

極数 CIRCUIT SIZE　　極数 CIRCUIT SIZE　　色 COLOR

△5 トレードマーク：MXプラス1文字のアルファベットにて構成
キャビティー番号：1桁から2桁の数字にて構成
金型番号：アルファベット1文字にて構成
TRADE MARK : FORMED BY MX AND 1 MORE
LETTER OF ALPHABET, BUT "J" MEANS JAPAN. (e.g. MXJ)
CAVITY No. : FORMED BY 1 - 2 DIGIT NUMBERS.
MOLD No. : FORMED BY 1 LETTER OF ALPHABET.

6. ELV 及び RoHS 適合品
ELV AND RoHS COMPLIANT.

番号 NO.	部品 PART	材質 MATERIAL
①	ウエハー WAFER	耐熱ナイロン、UL94V-0、色：シート2参照 HEAT RESISTANCE NYLON, UL94V-0, COLOR:SEE SHEET2
②	ソルダーピン SOLDER PIN	りん青銅 PHOSPHOR BRONZE 金メッキ :0.1 MICRO METER MINIMUM. GOLD PLATING ニッケル下地メッキ :1 MICRO METER MINIMUM. NICKEL UNDER PLATING
③	ネイル NAIL	黄銅 BRASS すずメッキ :1 MICRO METER MINIMUM. TIN PLATING ニッケル下地メッキ :1 MICRO METER MINIMUM. NICKEL UNDER PLATING

24	28	501571-50**	50
19	23	501571-40**	40
14	18	501571-30**	30
9	13	501571-20**	20
B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	CKT

CONNECTOR SERIES No. 501571-****

REVISED
EC NO: J2011-0742
DRWN:KWASHIO 2010/11/29
CH'KD:KASAKAWA 2010/12/02
APPR:NUKITA 2010/12/02
D
DESCRIPTION
REV

GENERAL TOLERANCES
(UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR ±3 °	

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: 5:1
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY	TRSUZUKI	DATE 2005/02/14
CHECKED BY	MYAGI	DATE 2005/02/14
APPROVED BY	ANODA	DATE 2005/02/14

TITLE
1.0 WIRE TO BOARD CONN.
2-ROW R/A WAFER ASSY
-LEAD FREE-

molex MOLEX INCORPORATED

MATERIAL NO. SEE TABLE
DOCUMENT NO. SD-501571-001
SHEET NO. 1 OF 2
SIZE A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

tb_frame_A3_J_AM_S
Rev. E 2006/04/15

EN-02DA(021)

緑 GREEN		青 BLUE		赤 RED		黒 BLACK		自然色 NATURAL		色 COLOR
—//—	501571-**76	—//—	501571-**74	—//—	501571-**72	—//—	501571-**71	501571-5007	501571-**09	50
—//—		—//—		—//—		—//—		501571-4007		40
—//—		—//—		—//—		—//—		501571-3007		30
501571-2056		501571-2054		501571-2052		501571-2051		501571-2007		20
EMBOSSED PACKAGE オーダー番号 ORDER NO.	CONNECTOR SERIES	EMBOSSED PACKAGE オーダー番号 ORDER NO.	CONNECTOR SERIES	EMBOSSED PACKAGE オーダー番号 ORDER NO.	CONNECTOR SERIES	EMBOSSED PACKAGE オーダー番号 ORDER NO.	CONNECTOR SERIES	EMBOSSED PACKAGE オーダー番号 ORDER NO.	CONNECTOR SERIES	CKT.

REV	DESCRIPTION
D	SEE SHEET 1 EC NO: J2011-0742 DRWN:KWASHIO 2010/11/29 CH'KD:KASAKAWA 2010/12/02 APPR:NUKITA 2010/12/02

GENERAL TOLERANCES
(UNLESS SPECIFIED)

10 UNDER	± 0.2
10 OVER 30 UNDER	± 0.25
30 OVER	± 0.3
ANGULAR ±3 °	

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: 5:1
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: TRSUZUKI	DATE: 2005/02/14
CHECKED BY: MYAGI	DATE: 2005/02/14
APPROVED BY: ANODA	DATE: 2005/02/14

TITLE
1.0 WIRE TO BOARD CONN.
2-ROW R/A WAFER ASSY
-LEAD FREE-

molex MOLEX INCORPORATED

MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-501571-001
SHEET NO.: 2 OF 2

SIZE: A3

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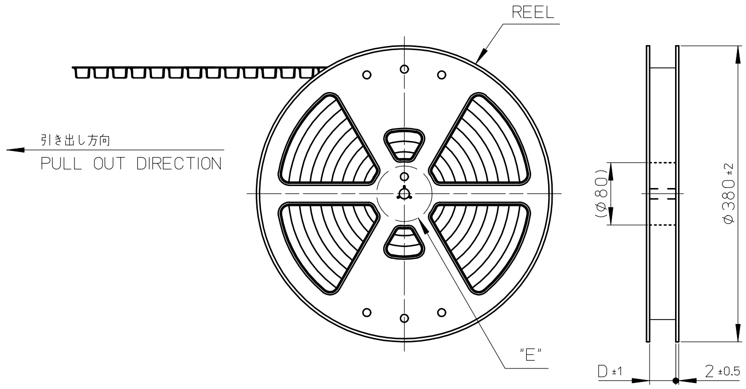
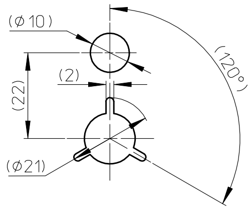




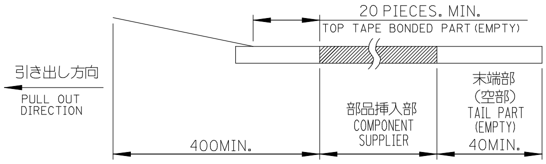
DETAIL "E"

NOTES

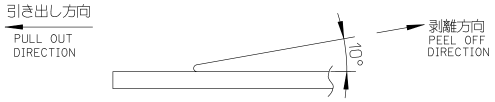
1. 製品詳細寸法については SD-501571-001 を参照ください。
   RE DETAILED DIMENSION, SEE SD-501571-001

2. 梱包数量： 800 個／リール
   NUMBER OF CONNECTORS : 800 PIECES/REEL

3. リードテープ長さ
   LEAD TAPE LENGTH



4. トップテープの剥離強度：0.1～1.3N(10.2 ～ 132.5gf)（剥離方向は下図参照）
   PEELING OFF FORCE OF TOP TAPE
   (PEELING DIRECTION AS SHOWN IN FOLLOWING FIGURE)
   尚、本規格値は、出荷時に適用。（但し、輸送時に剥離が発生しないこと）
   THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
   PEEL OFF SHOULD NOT BE ALLOWED, DURING TARANSPORTION.



5. 材料
   MATERIAL
   キャリアテープ：ポリプロピレン
   CARRIER TAPE:POLYPROPYLENE
   トップテープ：PET, PE, REF
   TOP TAPE
   リール：ポリスチレン〈リサイクル材を含む〉
   REEL : POLYSTYRENE 〈RECYCLE MATERIAL CONTAINED〉

6. 乾燥剤入り防湿梱包仕様になります。(501571-**07以外)
   INCLUDING DESICCANT TAPING PACKAGE.
   (BESIDES 501571-**07)

7. ELV 及び RoHS 適合品
   ELV AND RoHS COMPLIANT.

REV	DESCRIPTION
A	REVISED EC NO: J2011-0742 DRWN:KWASHIO 2010/11/29 CH'KD:KASAKAWA 2010/12/02 APPR:NUKITA 2010/12/02

GENERAL TOLERANCES (UNLESS SPECIFIED)	
10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	SCALE	DESIGN UNITS	
MM ONLY	---	METRIC	THIRD ANGLE PROJECTION

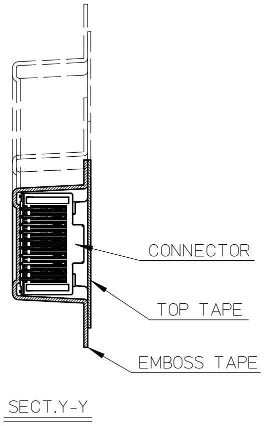
	DATE
DRAWN BY TRSUZUKI	2005/02/14
CHECKED BY MYAGI	2005/02/14
APPROVED BY ANODA	2005/02/14

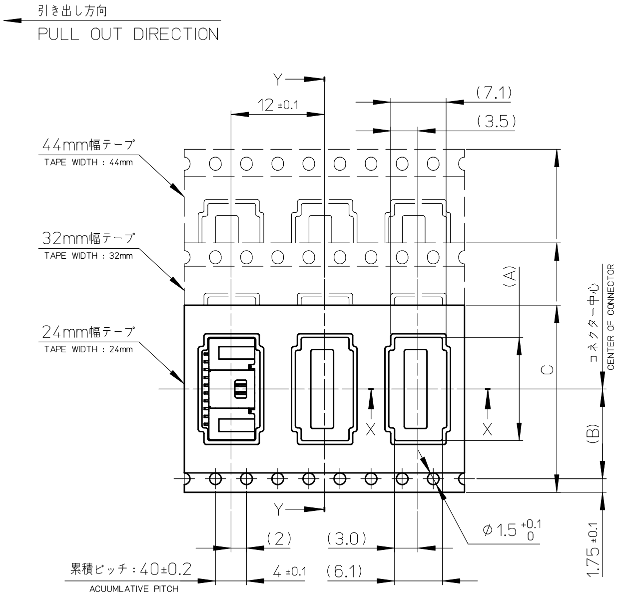
TITLE
1.0 WIRE TO BOARD CONN.
2-ROW R/A WAFER ASSY
EMBTP PKG -LEAD FREE-

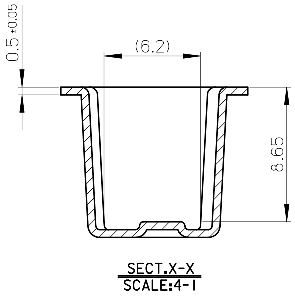
MOLEX INCORPORATED

MATERIAL NO.	DOCUMENT NO.	SHEET NO.
SEE SHEET 2	SD-501571-002	1 OF 3

SIZE A3







D	C CARRIER TAPE WIDTH	(B)	(A)	CONNECTOR SERIES NO.	EMBOSSED PACKAGE オーダー番号 ORDER NO.	CKTS.
45.5	44±0.3	20.2	28.3	501571-5009	501571-5007	50
			23.3	501571-4009	501571-4007	40
33.5	32±0.3	14.2	18.3	501571-3009	501571-3007	30
25.5	24±0.3	11.5	13.3	501571-2009	501571-2007	20
				501571-207*	501571-205*	

REV	DESCRIPTION		
A	SEE SHEET 1 EC NO: J2011-0742 DRWN:KWASHIO CH'KD:KASAKAWA APPR:NUKITA		2010/12/01 2010/12/02 2010/12/02

GENERAL TOLERANCES
(UNLESS SPECIFIED)

10 UNDER	± 0.2
10 OVER 30 UNDER	± 0.25
30 OVER	± 0.3
ANGULAR	±3 °

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
DRAWN BY TRSUZUKI DATE 2005/02/14	TITLE 1.0 WIRE TO BOARD CONN. 2-ROW R/A WAFER ASSY EMBTP PKG -LEAD FREE-		
CHECKED BY MYAGI DATE 2005/02/14			
APPROVED BY ANODA DATE 2005/02/14	molex MOLEX INCORPORATED		
MATERIAL NO. SEE CHART	DOCUMENT NO. SD-501571-002		SHEET NO. 2 OF 3
SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

緑 GREEN	青 BLUE	赤 RED	黒 BLACK	色 COLOR	
—//—	—//—	—//—	—//—	50	501571-**7*
—//—	—//—	—//—	—//—	40	
—//—	—//—	—//—	—//—	30	
501571-2056	501571-2054	501571-2052	501571-2051	20	
EMBOSSED PACKAGE オーダー番号 ORDER NO.				CKT.	CONNECTOR SERIES NO.

自然色 NATURAL	色 COLOR	
501571-5007	50	501571-**09
501571-4007	40	
501571-3007	30	
501571-2007	20	
EMBOSSED PACKAGE オーダー番号 ORDER NO.	CKT.	CONNECTOR SERIES NO.

REV	DESCRIPTION
A	SEE SHEET 1 EC NO: J2011-0742 2010/11/29 DRWN:KWASHIO 2010/12/02 CH'KD:KASAKAWA 2010/12/02 APPR:NUKITA

GENERAL TOLERANCES
(UNLESS SPECIFIED)

10 UNDER	± 0.2
10 OVER 30 UNDER	± 0.25
30 OVER	± 0.3
ANGULAR ±3 °	

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE	MM ONLY	
SCALE	---	
DESIGN UNITS	METRIC	
THIRD ANGLE PROJECTION		
DRAWN BY	TRSUZUKI	DATE 2005/02/14
CHECKED BY	MYAGI	DATE 2005/02/14
APPROVED BY	NUKITA	DATE 2010/12/02
MATERIAL NO.	SEE CHART	
SIZE	A3	

TITLE

1.0 WIRE TO BOARD CONN.
2-ROW R/A WAFER ASSY
EMBTP PKG -LEAD FREE-

molex MOLEX INCORPORATED

DOCUMENT NO. SD-501571-002

SHEET NO. 3 OF 3

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